

## CLAIMS

What is claimed is:

1. A microelectronic device comprising:  
a die, the die comprising a first side, a second side, and an edge;  
a first plate, the first plate coupled with the die; and  
a package, the die being coupled with the package.
2. The microelectronic device of claim 1, wherein the first plate exerts forces on the die to modify its effective coefficient of thermal expansion.
3. The microelectronic device of claim 2, where the first plate modifies the coefficient of thermal expansion of the die to make the coefficient of thermal expansion of die more closely match the coefficient of thermal expansion of the package.
4. The microelectronic device of claim 1, wherein the first plate comprises a hole, the die fitting within the hole, the edge of the die being coupled with an edge of the plate by the hole.
5. The microelectronic device of claim 4, wherein the edge of the die is soldered with the edge of the first plate.
6. The microelectronic device of claim 1, wherein a side of the die is coupled with a side of the first plate.
7. The microelectronic device of claim 1, further comprising a second plate coupled

- with the package.
8. The microelectronic device of claim 7, wherein the package is attached with the second plate by an adhesive.
  9. The microelectronic device of claim 7, wherein the first plate and second plate are constructed of the same material.
  10. The microelectronic device of claim 9, wherein the first plate and the second plate are constructed of copper.
  11. A method comprising;  
coupling a die with a first plate; and  
coupling the die with the package.
  12. The method of claim 11, wherein coupling the first plate with the die comprises modifying a coefficient of thermal expansion of the die.
  13. The method of claim 12, wherein modifying the coefficient of thermal expansion of the die makes the coefficient of thermal expansion of die more closely match a coefficient of thermal expansion of the package.
  14. The method of claim 11, wherein the plate comprises a hole, and wherein coupling the die with the first plate comprises placing the die within the hole and coupling an edge of the die with an edge of the plate by the hole.
  15. The method of claim 14, wherein coupling the die with the first plate comprises soldering the edge of the die with the edge of the first plate.

16. The method of claim 11, wherein coupling the die with the first plate comprises coupling a side of the die with a side of the first plate.
17. The method of claim 11, further comprising coupling a second plate with the package.
18. The method of claim 17, wherein coupling the second plate with the package comprises attaching the die and the second plate with an adhesive.
19. The method of claim 11, wherein the first plate and second plate are constructed of the same material.
20. The method of claim 19, wherein the first plate and the second plate are constructed of copper.
21. The product of the process of claim 11.
22. A computer comprising:
  - a bus;
  - a flash memory;
  - a microelectronic device comprising:
    - a die, the die comprising a first side, a second side, and an edge;
    - a first plate, the first plate coupled with the die; and
    - a package, the die being coupled with the package.
23. The computer of claim 22, wherein the microelectronic device is a processor.
24. The computer of claim 22, wherein the first plate modifies the coefficient of

thermal expansion of the die.

25. The computer of claim 22, where the first plate modifies the coefficient of thermal expansion of the die to make the coefficient of thermal expansion of die more closely match the coefficient of thermal expansion of the package.
26. The computer of claim 22, wherein the first plate comprises a hole, the die fitting within the hole, the edge of the die being coupled with an edge of the plate by the hole.
27. The computer of claim 26, wherein the edge of the die is soldered with the edge of the first plate.
28. The computer of claim 22, wherein a side of the die is coupled with a side of the first plate.
29. The computer of claim 22, further comprising a second plate coupled with the package.
30. The computer of claim 29, wherein the first plate and the second plate are constructed of copper.